Abstract:

This document serves as the primary documentation for the MIPI C-PHY Reference Termination Board (RTB), which is a reference termination test fixture used for performing MIPI C-PHY transmitter physical layer signaling measurements. (It is also used for measuring and calibrating the output of a reference signal source used for performing C-PHY receiver tolerance testing.) An overview of the features and general theory of operation of the board is discussed. Schematics are included, as well as typical performance characteristics in the form of...
S-Parameters, which are plotted against the MIPI C-PHY RX requirements to show the amount of margin.

**Introduction:**

The MIPI C-PHY Reference Termination Board (RTB) is a reference test fixture that is designed to emulate C-PHY receiver termination characteristics. Measurement data included in this document shows the C-PHY RTB is appropriate for testing products with symbol rates up to 2.5 Gsps. It is implemented in the form of an actively-controlled HS resistive load, which is enabled and disabled with the appropriate timings via FPGA control, according to the MIPI C-PHY LP signaling protocol. The fixture enables the measurement of most HS voltage and timing parameters using a single measurement setup, and the board is designed with very precisely controlled impedance and termination characteristics, in order to present a consistent, repeatable, termination environment to C-PHY transmitters for the purpose of performing MIPI-C-PHY transmitter physical layer conformance testing (and also for calibrating the output of lab signal sources when performing C-PHY receiver tolerance testing.) The board is meant to be used in conjunction with a real-time DSO and the necessary probing, accessories, and analysis software required for performing C-PHY measurements. The C-PHY Reference Termination Board, along with other boards offered at the UNH-IOL, were developed by the UNH-IOL’s MIPI test group which offers conformance and interoperability testing for MIPI Cameras, Displays, and Panels. For more information about general C-PHY test equipment requirements, as well as test definitions, setups, services, and procedures, please contact UNH-IOL at mipilab@iol.unh.edu.

**Background:**

Unlike many other high-speed serial technologies that utilize a static, 100-ohm differential reference termination environment, MIPI C-PHY is somewhat unique in that one of the key power-saving aspects of C-PHY is it’s the fact that the link utilizes a dynamic, switchable resistive termination at the receiver, which is enabled during the High-Speed (HS) mode of operation, and disabled to present an open termination environment during Low-Power (LP) mode. The HS and LP modes utilize different signaling schemes, with different voltage levels. The LP mode of operation is designed such that data can still be communicated between the two ends of the link, but at a much lower speed (20 Msymbols/sec max) than in HS mode, which is designed for operation between 0.8 Gsps and approximately 3 Gsps. This dual-mode functionality requires different receiver architecture than that typically found in other high-speed serial technologies. A simplified diagram of an example receiver implementation is shown in Figure 1 below (which has been reproduced from the C-PHY specification.)
In LP mode, all wires are operated single-ended, and are unterminated at the receiver. In this mode, minimal current flows between the two ends of the link (due to the lack of an RX termination), which reduces power consumption. In HS mode, the link utilizes 3-phase signaling with a common-point DC offset.

C-PHY devices switch between HS and LP modes via communication of a special LP state sequence, which signals an intent to transition to HS mode. When a receiver detects this mode it will enable its High-Speed (HS) line termination, which prepares the line for HS operation. The transmitter is then able to transmit data at the HS line rate for a period of time, after which a different control sequence is sent, which initiates a return to the LP mode of operation (whereby the receiver disconnects its HS termination at the appropriate time). This act of switching in and out of HS mode is typically called HS ‘burst mode’ operation.
In most other high-speed serial technologies that utilize a static, 100-ohm differential termination environment with DC-balanced signaling, it is common to use the test equipment input ports as the reference termination load for measurements, as the front end inputs of most pieces of test equipment are 50-ohm terminated, which effectively looks like a 50-ohm resistance to ground. By splitting the differential signal into two halves, and terminating each half into 50 ohms, a 100-ohm differential termination is achieved. This is typically the approach used for technologies like SATA, SAS, PCI Express, XAUI, 10GBASE-CX4, etc. For all of these standards, the test equipment basically provides a common, reference termination environment which is relatively consistent between different pieces of test equipment, as the termination specifications for the inputs of lab test equipment are typically very tightly controlled.

C-PHY however, presents a somewhat unique challenge, as there are two main factors that prevent using the test equipment (oscilloscope in this case) as the reference termination. The first is simply the presence of the switching open/100-ohm differential receiver termination, which no standard test instrument is capable of duplicating. The second factor is the fact that the HS mode of C-PHY expects the receiver to be AC coupled to ground, so that a DC common-point offset may be applied to the HS signal. If the HS differential signal is split and sent into two 50-ohm input ports of a DSO, the transmitter’s common-point signal component does not see an AC-coupled path to ground. This is not the termination for which the transmitter was designed, and thus prevents this type of measurement setup from being used.

Another measurement approach that is used to measure high-speed serial signals is to terminate the desired signal with an external termination load, and then probe the signal at that termination point using a high-impedance active differential probe. These high-performance probes use active circuitry to observe the signal under test without disturbing the signal itself, or causing excessive additional loading to the transmitter.

In this environment, the quality of the signal observed depends heavily on the electrical characteristics and quality of the external termination element used to terminate the line, as well as the quality of the means used to physically attach the termination element (typically a resistor) to the line. Hand-soldering of discrete components to a transmitter output port is typically not precise enough to produce consistent, repeatable results. Furthermore, this still does not address the switching nature of the C-PHY termination environment. Because of these issues, and the need to demonstrate accurate, repeatable physical layer measurements for C-PHY, there arose a need for a specialized, laboratory-grade termination solution for C-PHY test purposes.
The Solution:

To meet the need for a single common reference termination solution for C-PHY, the C-PHY Reference Termination Board (RTB) was developed, and is intended to serve as a common reference test fixture to facilitate consistent and repeatable conformance measurements of MIPI C-PHY signaling, for both conformance and characterization purposes.

A detailed image of the RTB is shown in the figure below, with icons highlighting several of the key features, which are described in further detail below.

![Figure 2: Detailed View of RTB (Top Side)](image)

Features:

Several key features of the RTB highlighted in Figure 2 above are:
1) SMP Inputs with Recommended Spacing and Lane Ordering:

The RTB uses standard SMP RF connectors. This is the means by which the RTB is connected to the Device Under Test (DUT). The RTB supports up to four C-PHY Lanes.

The spacing of the SMP connectors is 400-mil, center-to-center, for all connectors. The Lane ordering is (reading right to left in Figure 2 above): Lane0A, Lane0B, Lane0C, Lane1A, Lane1B, Lane1C, Lane2A, Lane2B, Lane2C, Lane3A, Lane3B, Lane3C.

2) Controlled-Impedance SMP Launches:

In order to optimize the connection path between devices, care must be taken to minimize impedance discontinuities that can occur at and around the SMP connectors of test boards. The area where the signal transitions from the pin of the SMP connector into the PCB trace is commonly called the launch. Poor quality SMP connectors, and/or poor PCB launch design can result in impedance discontinuities that will cause reflections to occur, resulting in reduced signal integrity, and other signaling artifacts, which are not acceptable when trying to make accurate measurements. The RTB uses a specially designed launch, customized for the specific SMP connector used, which minimizes the impedance discontinuity introduced by the SMP connectors. By using controlled launches on both the RTB and the DUT’s evaluation PCB, signals can pass through the SMP interface between boards with minimal degradation.

3) Active-Switching Termination Structure:

The small components seen just after the launch structure make up the HS termination structure. The structure for each Lane consists of three ADG8611 Ultrafast 4ns Single-Supply Comparators (which buffer the signal and are used to determine the high/low state of the line in LP mode), and three ADG902 Wideband 1GHz CMOS Switches, which perform the actual switching of the HS termination resistor (commonly referred to as ZID in the C-PHY specification), which is also implemented as part of the termination structure (see the small SMD resistors located between the switches/comparators, and the SMP launches).

The termination structures are specifically designed to be located as near to the SMP launches as possible, in order to minimize the excess trace length, and hence the capacitive loading seen by the DUT transmitter.

4) FPGA for Termination Control and Timing:

The termination switch structure alone is not sufficient to accomplish the switching operation. The purpose of the ADG8611 comparators is actually to sense the line and determine the LP line state during regular DUT operation. The output of the comparators is sent to the inputs of the FPGA, which is programmed to understand the LP signaling protocol, and looks for the proper ‘HS-entry’ sequence of LP states (LP-11/LP-01/LP-00), at which point it triggers the...
ADG902 switches to close and enable the HS termination resistor (ZID), in preparation for HS mode.

Once HS mode is enabled, the FPGA is programmed to look for the end of the HS burst (signaled by a return to the LP-11 state), at which point it disconnects the HS termination by deactivating the ADG902 switches.

5) Manual Override Dipswitches:

Because there are cases where it may be necessary to force the HS termination on or off, the dipswitches (SW1) on the RTB may be used to override the FPGA control, and manually force the HS terminations on or off.

The dipswitches allow independent control of Lane 0 and the group of Lane 1 through Lane 3, and work as follows:

- **DIPSW8**: ON: Lane 0 Termination always ON
- **DIPSW7**: ON: Lane 0 Termination always OFF
- **DIPSW6**: ON: Lane 1/2/3 Termination always ON
- **DIPSW5**: ON: Lane 1/2/3 Termination always OFF

For example, if you want to force the Lane 0 termination ON, then you would turn DIPSW8 to ON, and rest of switches to OFF.

6) Power Supply (USB):

The RTB receives power via a standard USB connection to any USB host port. (Note the USB connection is only used to supply power, and does not perform data transfer of any kind.)

The 5V supply voltage from the USB port is stepped down to 3.3V via the LM1117T regulator, which supplies power to all of the other active components on the board.

7) Comparator Reference Level Adjustment:

The three comparators per Lane are used to buffer the incoming signals, and effectively make a digital copy of each single-ended LP signal, which is sent back to the FPGA. The
Comparators compare the observed line level against a reference voltage level, and output a logic 1 or 0 if the line level is higher or lower than the reference voltage, respectively.

The comparator reference level is set to 0.6V by default, as this is one-half of the typical LP signaling level of approximately 1.2V. The FPGA is programmed to enable the HS termination at a specific time after the last falling LP edge of the HS entry sequence (LP-11/LP-10/LP-00). In rare cases where the FPGA does not appear to be enabling the HS termination at the proper time, it may be possible to adjust this value by modifying the comparator’s reference voltage level, which may have some effect if the LP edges of the DUT have an especially slow fall time. (Again, this should never really be necessary under typical conditions.) The comparator reference level can be measured using a voltmeter between vias marked ‘GND’ and ‘TRIG’, located near the blue potentiometer. The level can then be adjusted with the blue potentiometer, using a small screwdriver.
Impedance and S-Parameter Data:

The following pages contain impedance profile data and S-Parameter return loss data for Lane 0 of the RTB. Where applicable, the values are plotted against the C-PHY HS-RX S-Parameter requirements (i.e., the data is presented as if the RTB were tested as an actual C-PHY receiver device.)

Data is presented for Lane 0. The characteristics for the remaining 3 lanes is not shown because they are identical to Lane 0.

Note: The raw S-Parameter data source files used to generate these plots are available (for simulation purposes, etc), and can be obtained by contacting UNH-IOL at mipilab@iol.unh.edu.
Lane 0 AB: Differential Impedance Profile and Return Loss (2.5 Gsps)
Lane 0 AB: Common-Mode Impedance Profile and Return Loss (2.5 Gsps)
Lane 0 AB: Differential Impedance Imbalance (2.5 Gsps)
Lane 0 BC: Differential Impedance Profile and Return Loss (2.5 Gsps)

Test 3.2.14: HS-RX Diff. Impedance Profile (TDD11) and ZID

Test 3.2.1: HS-RX Differential Return Loss (SDD11)
Lane 0 BC: Common-Mode Impedance Profile and Return Loss (2.5 Gsps)

Test 3.2.2: HS-RX Common-Mode Impedance Profile (TCC11) (Informative)

Test 3.2.2: HS-RX Common-Mode Return Loss (SCC11)

Min Margin: 700MHz (1.85dB)
Lane 0 BC: Differential Impedance Imbalance (2.5 Gsps)
Lane 0 CA: Differential Impedance Profile and Return Loss (2.5 Gsps)
Lane 0 CA: Common-Mode Impedance Profile and Return Loss (2.5 Gsps)
Lane 0 CA: Differential Impedance Imbalance (2.5 Gsps)